







Attenuator Full Flange 100 Watts

General Specifications

Resistive Element

Substrate Beryllium oxide ceramic

Cover Alumina Ceramic

Mounting Flange Copper, Nickel plated per QQ-N-

Thick film

290

Lead(s): 99.99% pure silver (.006" thick)

Features:

- DC -See Chart
- 100 Watts
- BeO Ceramic
- Non-Nichrome Resistive Element
- Low VSWR
- Welded Silver Leads
- Lead Length .150 in min, .210 in Typical
- 100% Tested
- RoHS Compliant

Electrical Specifications

Attenuation Range: 1, 2, 3, 4, 5, 6, 9, 10, 20 or 30 dB

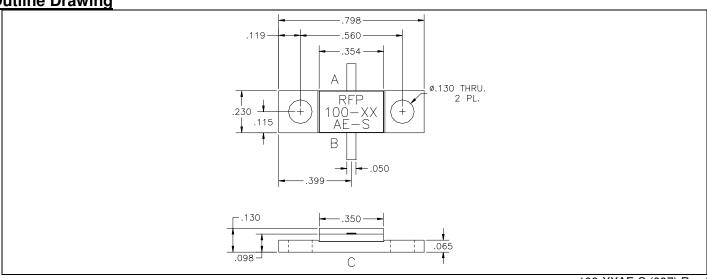
Frequency Range; DC – See Chart
Power: 100 Watts
VSWR See Chart

Note: Tolerance is ± 0.010 ", unless otherwise specified. Designed to meet of exceed applicable portions of MIL-E-5400. Operating temperature is -55 $^{\circ}$ C to 150 $^{\circ}$ C (see chart for derating temperatures).

All dimensions in inches.

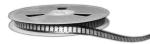
Specifications subject to change with out notice.

Outline Drawing



100-XXAE-S (097) Rev D





Available on Tape and Reel For Pick and Place Manufacturing. USA/Canada: (315) 432-8909 Toll Free: (800) 544-2414 Europe: +44 2392-232392





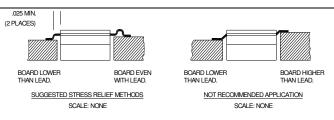
Typical Performance:

SPECIFICATION CHART							
ATTENUATION	FREQ.	VSWR	VALUE (A-B)	VALUE (A-C)	VALUE (B-C)	TOL.	RFP P/N
1dB ±0.4	DC-1GHZ.	1.45:1	5.8 Ω	435.9Ω	435.9Ω	±4%	RFP-100-1AE-S
2dB ±0.4	DC-1GHZ.	1.40:1	11.4Ω	220.7Ω	220.7Ω	±4%	RFP-100-2AE-S
3dB ±0.4	DC-1GHZ.	1.35:1	17.0 Ω	150.5Ω	150.5Ω	±4%	RFP-100-3AE-S
4dB ±0.3	DC-1GHZ.	1.30:1	22.6Ω	116.3Ω	116.3Ω	±4%	RFP-100-4AE-S
5dB ±0.3	DC-1GHZ.	1.25:1	28.0 Ω	96.0 Ω	96.0 Ω	±4%	RFP-100-5AE-S
6dB ±0.3	DC-1GHZ.	1.20:1	32.2 Ω	83.6 Ω	83.6 Ω	±4%	RFP-100-6AE-S
9dB ±0.3	DC-1GHZ.	1.20:1	47.6Ω	64.4 Ω	64.4 Ω	±4%	RFP-100-9AE-S
10dB ±1.2	DC-2GHZ.	1.25:1	52.0∩	61.0 Ω	61.0 Ω	±4%	RFP-100-10AE-S
20dB ±0.5	DC-2.5GHZ.	1.20:1	81.7Ω	50.9 Ω	50.9 Ω	±4%	RFP-100-20AE-S
30dB ±2.0	DC-2GHZ.	1.20:1	92.5 Ω	49.6 Ω	49.6 Ω	±4%	RFP-100-30AE-S

Power De-rating:

POWER DERATING 100 POWER 75 RATED 50 25 Ы % 0 25 50 75 100 125 150 P.C.B. SOLDER INTERFACE TEMPERATURE—*C

Mounting Footprint and Procedure:



SUGGESTED MOUNTING PROCEDURES:

- MAKE SURE THAT THE DEVICES ARE MOUNTED ON FLAT SURFACES (.001" UNDER THE DEVICE) TO OPTIMIZE THE HEAT TRANSFER.
- 2. DRILL & TAP THE HEATSINK FOR THE APPROPRIATE THREAD SIZE TO BE USED.
- 3. COAT HEATSINK WITH A MINIMUM AMOUNT OF HIGH QUALITY SILICONE GREASE (.001" MAX. THICKNESS).
- 4. POSITION DEVICE ON MOUNTING SURFACE & SECURE USING SOCKET HEAD SCREWS, FLAT & SPLIT WASHER. TORQUE SCREWS TO THE APPROPRIATE VALUE. MAKE SURE THAT THE DEVICE IS FLAT AGAINST THE HEATSINK. (CARE SHOULD BE TAKEN TO AVOID UPWARD PRESSURE OF THE LEADS TOWARDS THE LID).
- SOLDER LEADS IN PLACE USING APPROPROATE SOLDER WITH A CONTROLLED TEMPERATURE IRON.

** FOR MORE DETAILS CONTACT FACTORY **

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